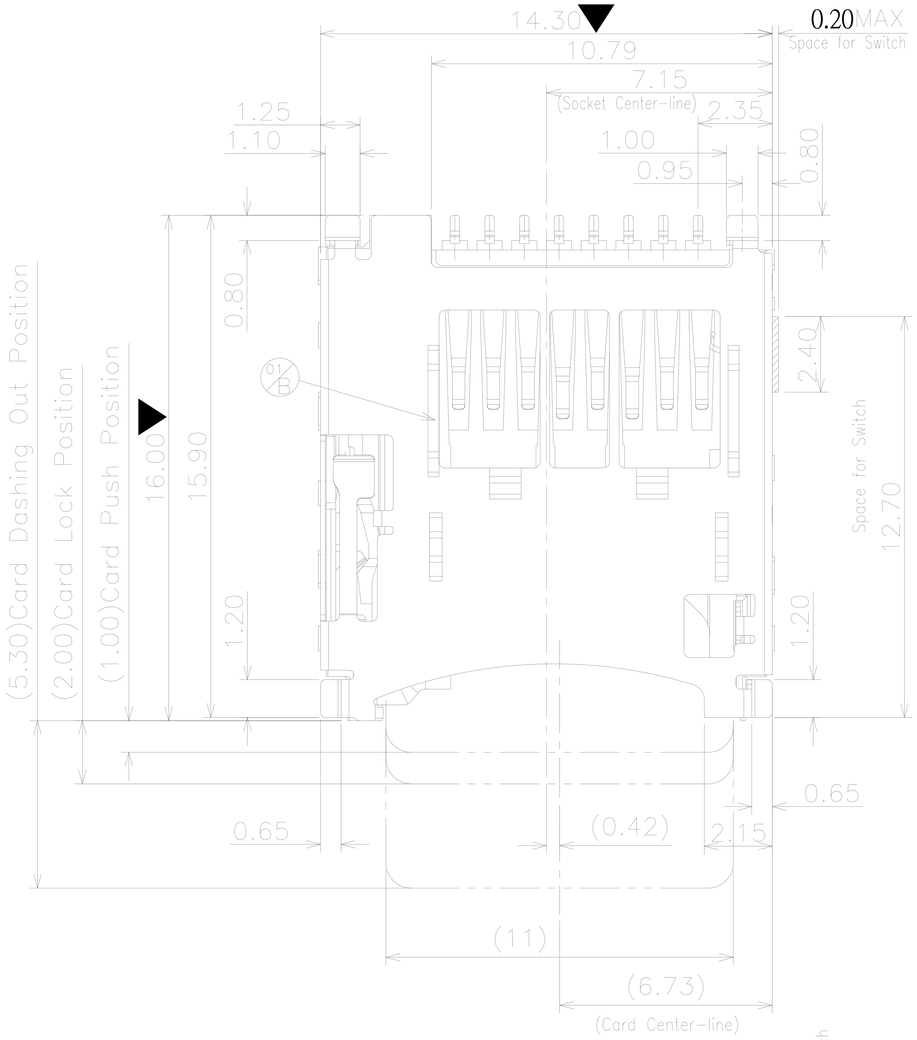
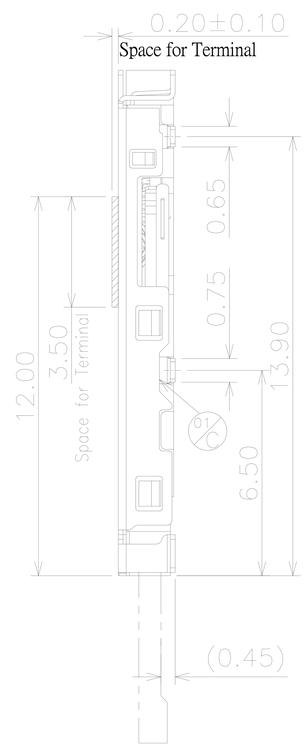
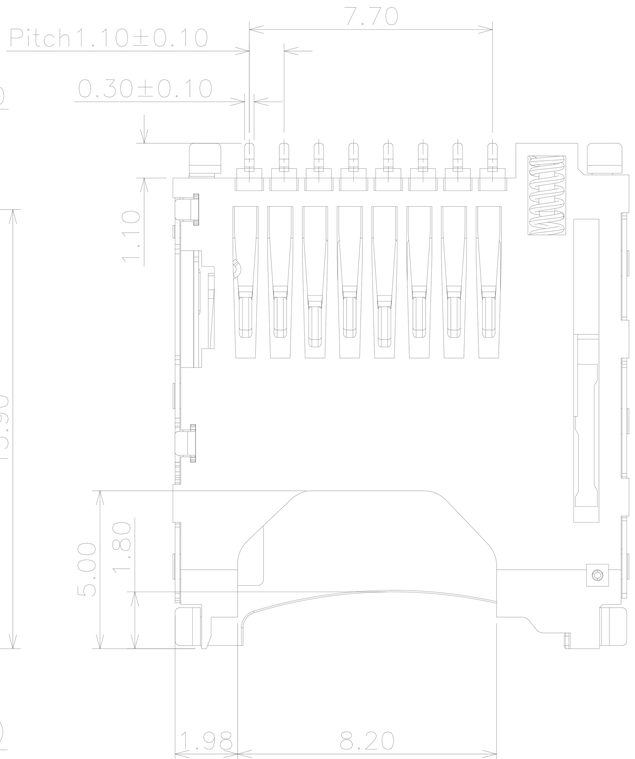
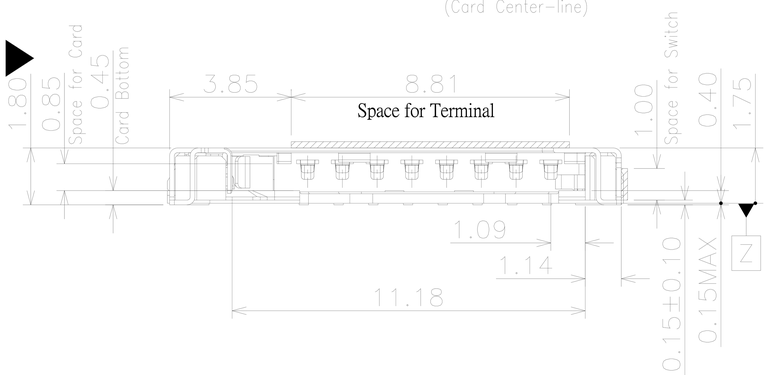


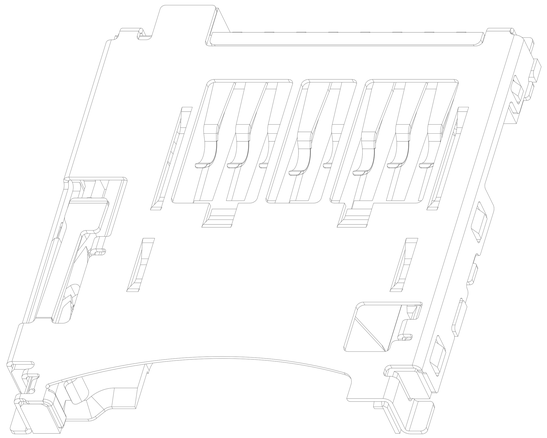






Circuit Diagram for Detect Switch

CARD OUT	Switch A — Switch A
CARD LOCK	Switch A — Switch A
CARD PUSH END	Switch A — Switch A



LTR	REVISION RECORD	ECR	ECN	DRG	CHK	DATE
C	減小鐵殼邊料,取消LOGO規格.			TaiKun_Peng		2015/01/12
B	加大鐵殼孔			TaiKun_Peng		2014/12/04
A1	图面更新					2014/06/04
A	INCREASE 3u" SPECIFICATION			guoqiaoyuan		2011/01/04

CUSTOMER COPY

FORM NO.:

APPROVED BY:

CHECKED BY:

DRAWING BY:

GENERAL TOLERANCES

.X:	±0.25
.XX:	±0.20
.XXX:	±0.15
X:	±4.0°
X.X:	±3.0°
X.XX:	±2.0°

SHEET 1 OF 2

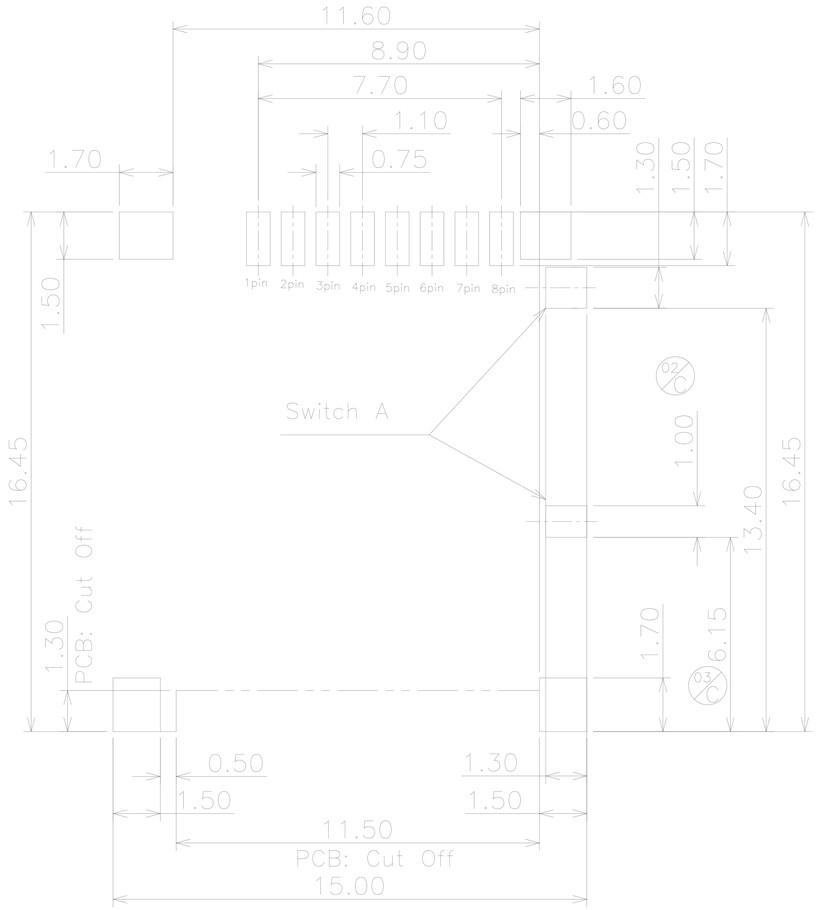
東莞市訊普電子科技有限公司

TITLE: MicroSD Memory Card Socket Reverse Type

PART NO: TF-114

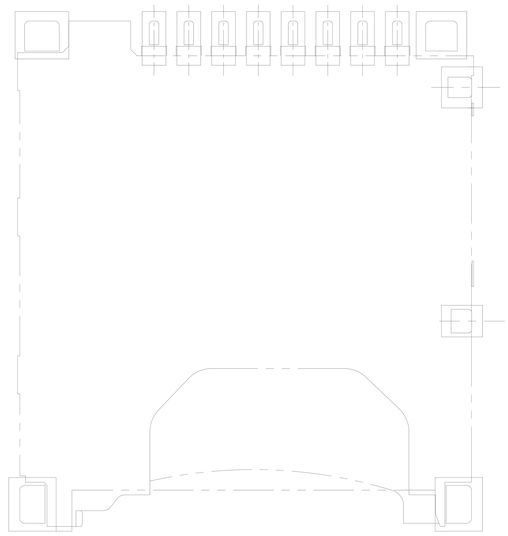
DWG NO:

REV: C UNIT: mm SCALE : 1:1 Sheet A3

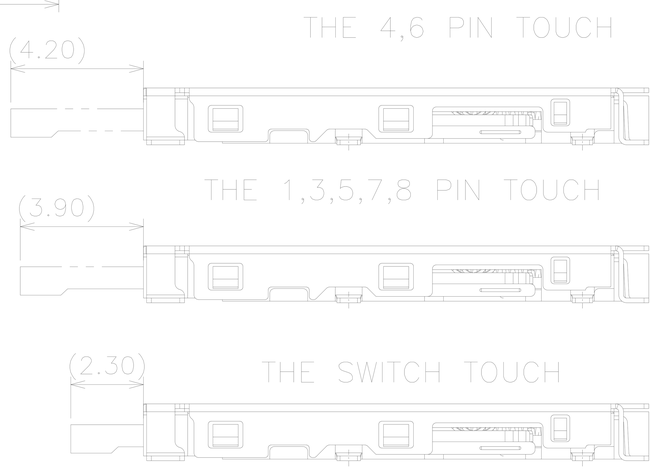


Recommended PCB Pattern Layout

General Tolerance: ±0.05



Connector on Pattern



Note:

1.Material: See Table

2.Finishes: See Table

2-1 Contact: Nickel Underplated

3u" Gold Plating on Contact Area,Gold Flash on Solder Tail

2-2 Switch & Detect: Nickel Underplated

5u" Gold Plating on Contact Area

2-3 Shell: Gold Flash Over Nickel Underplated on Solder Pad

3.Coplanarity of Soldertails : 0.10MAX.

Misalignment of Solder Tail From "Z"

Upper Direction 0.05 MAX. , Lower Direction 0.1 MAX.

4.Mechanical Specification:

Repeated 10000 Times Mating and Unmating Cycles and Still Meet Electrical Characteristics

5.Electrical Specification:

5-1 Rated Current (Per Contact): 0.5Amps MAX and Temperature Rise Should be 30°C MAX.

5-2 Insulation Resistance(LR):1000 Megohms MIN.

5-3 Dielectric With Standing Voltage: 500VAC

5-4 Contact Resistance : 100 Milliohms MAX.

6."▼" sign, for the QC testing and focus IPQC

LTR	REVISION RECORD	ECR	ECN	DRG	CHK	DATE
C	減小鐵殼邊料,取消LOGO規格.			TaiKun_Peng		2015/01/12
B	加大鐵殼孔			TaiKun_Peng		2014/12/04
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A	INCREASE 3u" SPECIFICATION			guoqiaoyuan		2011/01/04

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GENERAL TOLERANCES	
.X:	±0.25
.XX:	±0.20
.XXX:	±0.15
X:	±4.0°
X.X:	±3.0°
X.XX:	±2.0°

SHEET 2 OF 2

東莞市訊普電子科技有限公司

TITLE:	MicroSD Memory Card Socket Reverse Type
PART NO:	TF-114
DWG NO:	
REV: C	UNIT: mm SCALE : 1:1 Sheet A3